

ABSTRACT

An electroplating apparatus for a non-circular substrate, comprising: a central electrode region, circular in shape, sized to be the inscribed circle of the non-circular substrate, a central electrode being arranged in the central electrode region, and the central electrode fully filling the central electrode region; a peripheral electrode region, arranged around the central electrode region, with an outer periphery of the peripheral electrode region sized to be the circumscribed circle of the non-circular substrate, a peripheral electrode being arranged in the peripheral electrode region, and the peripheral electrode including a plurality of block electrodes that fully fill the peripheral electrode region; a power supply module, including a plurality of power supplies for supplying power to the central electrode and the peripheral electrode; and a control module, configured to detect the rotational position of the substrate, calculate the current magnitude required by each block electrode at present, and feed the current magnitude back to the power supply module to adjust the current magnitude.